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**Aehr Test Systems to Participate in Sixth Annual NYC Investor Summit**

**Fremont, CA (November 28, 2017) - Aehr Test Systems (NASDAQ: AEHR)**, a worldwide supplier of semiconductor test and burn-in equipment, today announced that Gayn Erickson, President and CEO, is scheduled to participate in the Sixth Annual NYC Investor Summit 2017, taking place December 6, 2017 at Le Parker Méridien Hotel in New York City.

Mr. Erickson commented, “We look forward to discussing how our advanced test and burn-in systems are helping companies that supply devices into the automotive sensor, mobile communications, IC, and Internet of Things markets meet the higher quality and reliability needs of these markets, where safety, security and assurance of user confidence are absolutely critical.”

**About the NYC Summit**

The NYC Summit is hosted by executive management from participating companies and will feature a “round-robin” format consisting of small group meetings, each 30 minutes in duration. During the event, investors and analysts will have the opportunity to meet with up to 10 of the 14 management teams during the 30-minute group meeting sessions, as well as opportunities to meet with additional management teams during the breakfast and lunch networking sessions. The NYC Investor Summit is by invitation only and is open to accredited investors and publishing research analysts.

**About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic, optical and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, incremental capacity needs, and new opportunities for Aehr Test products in package, wafer level, and singulated die/module level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX-P™ families of test and burn-in systems and FOX WaferPak Aligner, FOX-XP WaferPak Contactor, and FOX DiePak® Carrier. The ABTS system is used in production and qualification testing of packaged parts for lower power and higher power logic devices as well as all common types of memory devices. The FOX-XP system is a full wafer contact and singulated die/module test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers, systems-on-a-chip, and integrated optical devices. The WaferPak contactor contains a unique full wafer probe card capable of testing wafers up to 300mm that enables IC manufacturers to perform test and burn-in of full wafers on Aehr Test FOX systems. The DiePak Carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of both bare die and modules. For more information, please visit Aehr Test System’s website at [www.aehr.com](http://www.aehr.com).

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